

# Schottky Barrier Rectifier, Trench-based

## NRTS10100PFS, NRVTS10100PFS

This TO-277 trench Schottky rectifier provides fast switching performance in a compact thermally efficient package. The TO-277 package provides an excellent alternative to the DPAK, offering thermal performance nearly as good in a package occupying less than half the board space. Its low profile makes it a good option for flat panel display and other applications with limited vertical clearance. The device offers low leakage over temperature making it a good match for applications requiring low quiescent current.

#### **Features**

- Package Provides Capability of Inspection and Probe After Board Mounting
- Low Forward Voltage Drop
- 175 °C Operating Junction Temperature
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### **Mechanical Characteristics:**

- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94-0 @ 0.125 in.
- Lead Finish: 100% Matte Sn (Tin)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260 °C Max. for 10 Seconds
- Device Meets MSL 1 Requirements

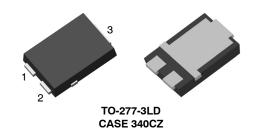
#### **Applications**

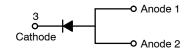
- Excellent Alternative to DPAK in Space-Constrained Automotive Applications
- Low Leakage for Higher Temperature Operation
- Output Rectification in Compact Portable Consumer Applications

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• Freewheeling Diode used with Inductive Loads

## SCHOTTKY BARRIER RECTIFIER, 10 AMPERES 100 VOLTS





#### **MARKING DIAGRAM**

T10100 AWLYW

T10100 = Specific Device Code A = Assembly Location

Y = Year
W = Work Week
WL = Wafer Lot

#### **ORDERING INFORMATION**

Device	Package	Shipping†
NRTS10100PFST3G	TO-277 (Pb-Free)	5000 / Tape & Reel
NRVTS10100PFST3G	TO-277 (Pb-Free)	5000 / Tape & Reel

† For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V <sub>RRM</sub> V <sub>RWM</sub> V <sub>R</sub>	100	V
Average Rectified Forward Current (T <sub>C</sub> = 162 °C)	I <sub>F(AV)</sub>	10	Α
Peak Repetitive Forward Current, (T <sub>C</sub> = 159 °C, Square Wave, Duty = 0.5)	I <sub>FRM</sub>	20	Α
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I <sub>FSM</sub>	120	Α
Storage Temperature Range	T <sub>stg</sub>	-65 to +175	°C
Operating Junction Temperature	TJ	-55 to +175	°C
ESD Rating (Human Body Model)		3B	
ESD Rating (Machine Model)		M4	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient (Assumes 600 mm <sup>2</sup> , 1 oz. copper bond pad on a FR4 board)	$R_{ hetaJA}$	69	°C/W
Thermal Resistance, Junction-to-Case, Top (Assumes 600 mm², 1 oz. copper bond pad on a FR4 board)	$R_{ heta JCT}$	60	°C/W
Thermal Resistance, Junction-to-Case, Bottom (Assumes 600 mm², 1 oz. copper bond pad on a FR4 board)	$R_{ heta JCB}$	2.0	°C/W

#### **ELECTRICAL CHARACTERISTICS**

Characteristic	Symbol	Тур	Max	Unit
Instantaneous Forward Voltage (Note 1)	VF	0.58 0.54 0.73 0.65	- - 0.78 0.70	V
Instantaneous Reverse Current (Note 1) (Rated dc Voltage, T <sub>J</sub> = 25 °C) (Rated dc Voltage, T <sub>J</sub> = 125 °C)	i <sub>R</sub>	5.6 4.5	100 51	μA mA
Junction Capacitance (V <sub>R</sub> = 1 V, T <sub>J</sub> = 125 °C, 1 MHz)	CJ	760	-	pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

<sup>1.</sup> Pulse Test: Pulse Width = 300  $\mu$ s, Duty Cycle  $\leq$  2.0%.

#### **TYPICAL CHARACTERISTICS**

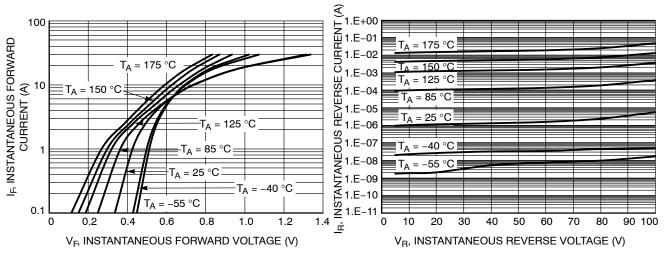


Figure 1. Typical Instantaneous Forward Characteristics

Figure 2. Typical Reverse Characteristics

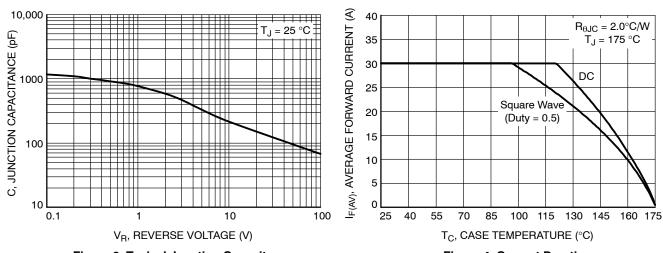


Figure 3. Typical Junction Capacitance

Figure 4. Current Derating

#### **TYPICAL CHARACTERISTICS**

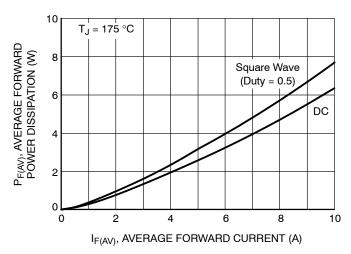


Figure 5. Forward Power Dissipation

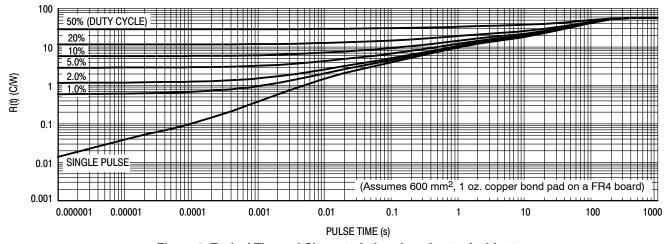


Figure 6. Typical Thermal Characteristics, Junction-to-Ambient

#### **REVISION HISTORY**

Revision	Description of Changes	Date
0	Initial datasheet release for production.	02/12/2020
1	Rebranded the Data Sheet to <b>onsemi</b> format.	10/27/2025
2	Corrected shipping quantity from 1500 to 5000.	11/12/2025

This document has undergone updates prior to the inclusion of this revision history table. The changes tracked here only reflect updates made on the noted approval dates.



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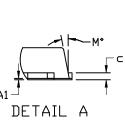
#### TO-277-3LD CASE 340CZ ISSUE A

# ISSUE A

**DATE 14 FEB 2020** 

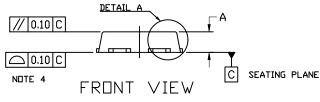


- 2. CONTROLLING DIMENSION: MILLIMETERS
- DIMENSIONS 6, 61,62,63,66 AND c TO BE MEASURED ON FLAT SECTION OF THE LEAD, BETWEEN 0.13 AND 0.25mm FROM LEAD TIP.
- 4. COPLANARITY APPLES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
- 5. POSITIONAL TOLERANCE APPLIES TO THE TERMINALS AND EXPOSED PAD.
- A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
- 7. DIMENSIONS D AND E TO BE DETERMINED AT DATUM PLANE C.



		MILLIMETERS		RS
	DIM	MIN.	N□M.	MAX.
~M°	Α	1.00	1.10	1.20
⊢с	A1		0.01	0.05
	b	1.13	1.18	1.28
	b1	0.70 REF		
	b2	1.98	2.03	2.13
Α	b3	1.20 REF		
	b4	0.71 REF		•
	c	0.20 REF		
	D	4.45	4.60	4.75
	D1	4.35	4.40	4.45
	D2	3.50	3.60	3.70

	MILLIMETERS		
DIM	MIN. NOM. MAX		MAX.
E	6.35	6.50	6.65
E1	6.05	6.10	6.15
E2	4.50	4.60	4.70
E3	3.84	3.94	4.04
E4	0.98 REF		
e	2.13 BSC		
К	0.85 REF		
K1	0.40 REF		
L	0.90	1.05	1.20
L1	0.02		
М	12°		12*



В

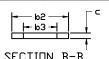
E1

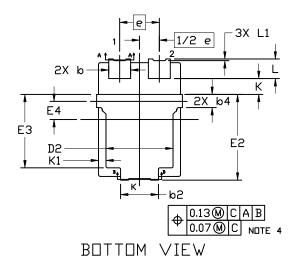
D1

Κ

THP VIFW







SECTION A-A	2FCLIUN B-B
3.90 - 2.33  -	
2.13	2,84 3.50 4.90 2X 1.48
REC□MMENDED	

MOUNTING FOOTPRINT

- For additional information on our Pb-Free strategy and soldering details, please download the IDN Semiconductor Soldering and Mounting Techniques Reference Manual, SIILDERRM/D.
- \*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present. Some products may not follow the Generic Marking.

GENERIC
<b>MARKING DIAGRAM</b>

XXXXXX = Specific Device Code

XXXXXX AWLYW

98AON97727G

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W = Work Week
WL = Wafer Lot

**DOCUMENT NUMBER:** 

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DESCRIPTION: TO-277-3LD

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